



**RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 1700**

PATENT

Attorney Docket No. 98124X205843
Client Reference No. 98124CON2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Wang et al.

Application No. 09/636,246

Filed: August 10, 2000

For: POLISHING SYSTEM WITH STOPPING
COMPOUND AND METHOD OF ITS USE

Art Unit: 1765

Examiner: Charlotte A. Brown

**AMENDMENTS TO CLAIMS
MADE IN RESPONSE TO OFFICE ACTION DATED NOVEMBER 19, 2002**

Amendments to existing claims:

1. (Amended) A system for polishing one or more layers of a multi-layer substrate that includes a first metal layer and a second layer comprising (i) a liquid carrier, (ii) at least one oxidizing agent, (iii) at least one polishing additive that increases the rate at which the system polishes at least one layer of the substrate, (iv) at least one stopping compound with a polishing selectivity of the first metal layer:second layer of at least about 30:1, wherein the stopping compound is a cationically charged nitrogen containing compound selected from [compounds comprising amines, imines, amides, imides] the group consisting of a polyetheramine, polyethylenimine, N₄-amino(N,N'-bis-[3-aminopropyl]ethylenediamine), 4,7,10-trioxatridecane-1,13-diamine, 3,3-dimethyl-4,4-diaminodicyclohexylmethane, 2-phenylethylamine, N,N-dimethyldipropylenetriamine, 3-[2-methoxyethoxy]propylamine, dimethylaminopropylamine, 1,4-bis(3-aminopropyl)piperazine, isophoronediamine, hexamethylenediamine, cyclohexyl-1,3-propanediamine, thiomine, (aminopropyl)-1,3-propanediamine, tetraethylenepentamine, tetramethylbutanediamine, propylamine, diaminopropanol, aminobutanol, (2-aminoethoxy)ethanol, and mixtures thereof, and (v) a polishing pad and/or an abrasive.